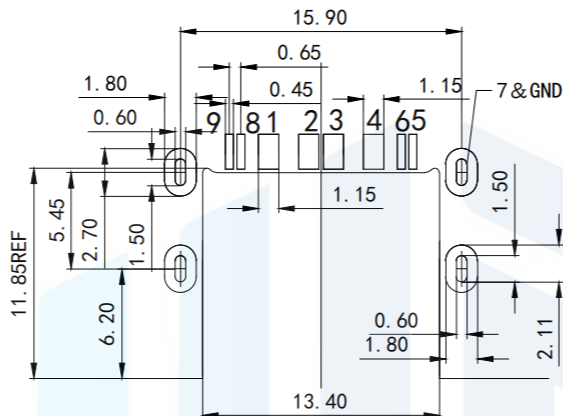
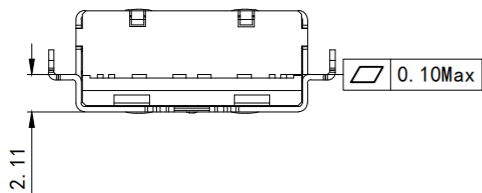
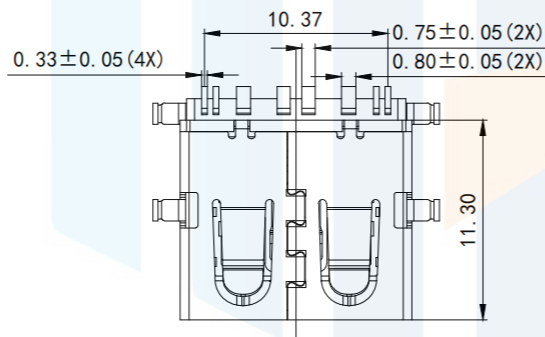


RoHS2.0
Compliant

H=2.11MM

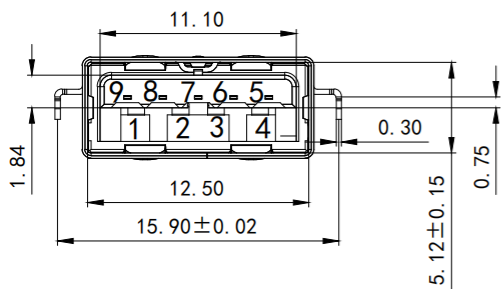
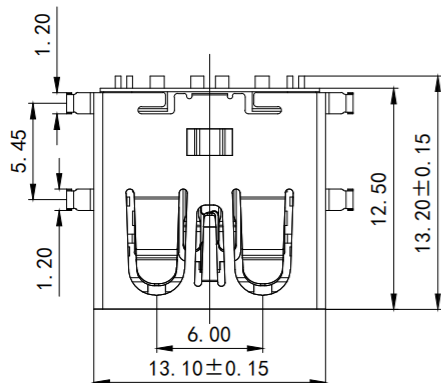


TOLERANCE: ± 0.05 , RECOMMENDED PCB LAYOUT (TOP VIEW)

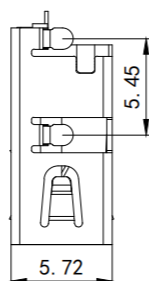


NOTE:

- MATERIAL:**
1.1 INSULATOR: LCP+30%GF, UL94V-0, 1.2 CONTACT 1~4PIN: C5191R/H,
1.3 CONTACT 5~9PIN: C5191R/H,
1.4 SHELL: SUS201
- PLATING:**
2.1 CONTACT: SELECTIVE GOLD PLATED ON CONTACT AREA 100u" Min. MATTE TIN PLATED ON SOLDER TAIL 50u" Min. NICKEL UNDER-PLATED
2.2 SHELL: 50u" Min, NICKEL PLATED OVERALL
- CHARACTERISTICS:**
3.1 ELECTRICAL CHARACTERISTICS; CONTACT RESISTANCE: 30mΩ
MAXIMUM CONTACT CURRENT RATING: 3A DIELECTRIC WITHSTANDING VOLTAGE: 500 V R. M. S. INSULATION RESISTANCE 1000 MEGOHMS
MIN OPERATING TEMPERATURE: -25°C? +85°C
3.2 MECHANICAL: MATING FORCE: 3.57Kg. Max. UNMATING FORCE: 1.02Kg. Min.
- RoHS COMPLIANT**
- WAVE SOLDER:** THE CONNECTOR SHALL BE MOUNTED ON THE PCB. THE TEMPERATURE OF THE SOLDER SHALL BE 270 ± 5 °C AND IMMERSION DURATION 5 SECONDS.



Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield



TOLERANCE			东莞市恒祺电子科技有限公司 Dongguan Hengqi Electronic Technology Co., Ltd https://www.hq-dz.com phone: 15812872448		
X. XXX	± 0.05				
X. XX	± 0.15	TITLE: USB3.1 A/F 沉板2.11直边 4定位脚外移(10GB)			
X. X	± 0.20				
X.	± 0.30	PART NO: USB3.1-V175 DRAWING NO: 12.5*13.1*5.72			
ANGLE	$\pm 5.0^\circ$				
PROTECTON		DRAWN:	DATE:	18-10-08	UNIT: mm
		CHECKED:	DATE:	18-10-08	SCALE: FULL
		APPROVED:	DATE:	18-10-08	SIZE: A4